

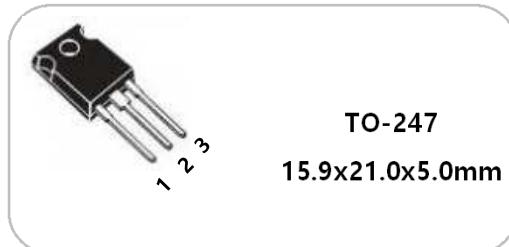


### General description

Symbol	Value
$V_{DSS}$ @ $T_c=25^\circ\text{C}$	Min 650V
$I_D$ @ $T_c=25^\circ\text{C}$	40.8A
$R_{DS(on)}$	Typ 70mΩ
$Q_G$	Typ 80nC

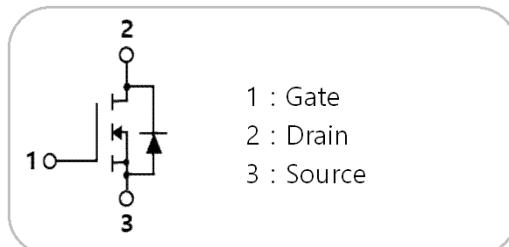


### Package



### Features

- Low resistance
- Avalanche rated
- Low package inductance



### Applications

- Power factor correction
- Server power supplies
- Telecom power supplies
- Inverters
- Motor control



### Maximum Ratings ( $T_c = 25^\circ\text{C}$ )

Parameter	Symbol	Test condition	Value	Unit
Drain - source voltage	$V_{DSS}$	$T_c=25^\circ\text{C}$	650	V
Gate - source voltage	$V_{GS}$	-	$\pm 30$	V
Continuous drain current	$I_D$	$V_{GS}=20\text{V}$ , $T_c=25^\circ\text{C}$	40.8	A
		$V_{GS}=20\text{V}$ , $T_c=100^\circ\text{C}$	25.8	A
Pulsed drain current	$I_{D(\text{pulse})}$	Pulse width $t_p$ limited by $T_{j,\text{max}}$	175	A
Avalanche energy, single pulse	$E_{AS}$	$I_D=7.2\text{A}$ , $V_{DD}=50\text{V}$	650	mJ
Avalanche energy, repetitive	$E_{AR}$	$I_D=7.2\text{A}$ , $V_{DD}=50\text{V}$	1.0	mJ
Avalanche current, repetitive	$I_{AR}$	-	8.7	A
Power dissipation	$P_D$	$T_c=25^\circ\text{C}$	275	W
Operating and storage temperature range	$T_j, T_{stg}$	-	-55 to 150	°C




**Electrical characteristics ( $T_j = 25^\circ\text{C}$ )**

Parameter	Symbol	Test condition	Value			Unit
			Min	Typ	Max	
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=1\text{mA}$	650	-	-	V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0, T_j=25^\circ\text{C}$	-	-	10	uA
		$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0, T_j=150^\circ\text{C}$	-		100	uA
Gate-source leakage current	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	200	nA
		$V_{\text{GS}}=-20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	200	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=100\text{uA}$	2.5	3.2	4.0	V
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=15.9\text{A}$	-	70	80	$\text{m}\Omega$
Gate input resistance	$R_G$	f=1MHz, open drain	-	1.0	-	$\Omega$
Input capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, f=1\text{MHz}$	-	4300	-	pF
Output capacitance	$C_{\text{oss}}$		-	100	-	
Reverse transfer capacitance	$C_{\text{rss}}$		-	17	-	
Gate-source charge	$Q_{\text{GS}}$	$V_{\text{DS}}=480\text{V}, V_{\text{GS}}=0 \text{ to } 10\text{V}, I_{\text{D}}=15.9\text{A}$	-	17	-	nC
Gate-drain charge	$Q_{\text{GD}}$		-	28	-	
Total gate charge	$Q_G$		-	80	-	
Turn on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=480\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=15.9\text{A}, R_G = 1\Omega$	-	20	-	ns
Rise time	$t_r$		-	25	-	
Turn off delay time	$t_{\text{d}(\text{off})}$		-	95	-	
Fall time	$t_f$		-	25	-	

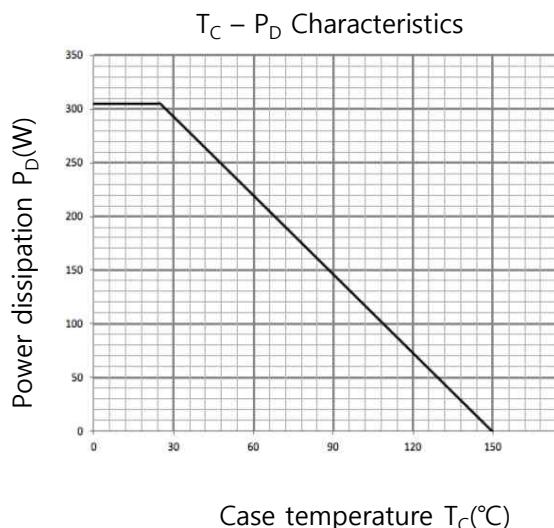
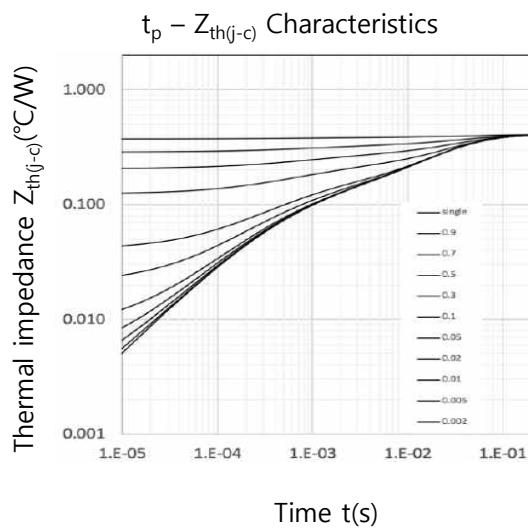


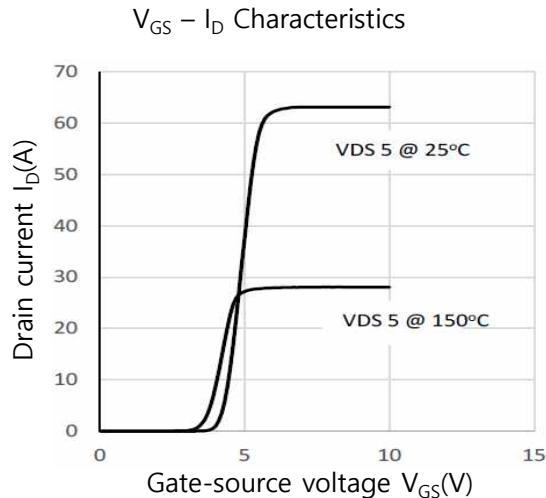
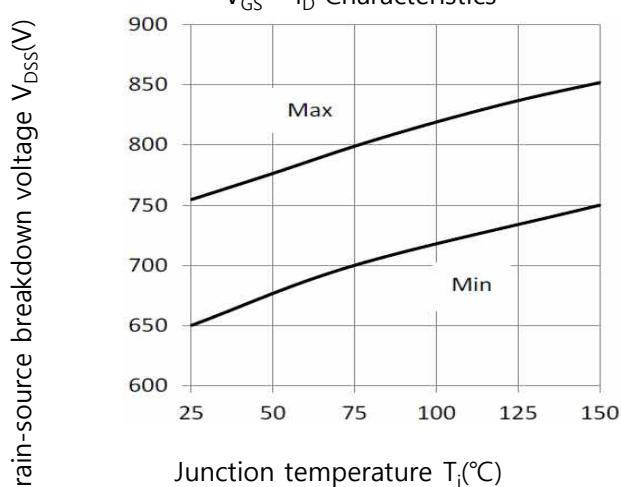
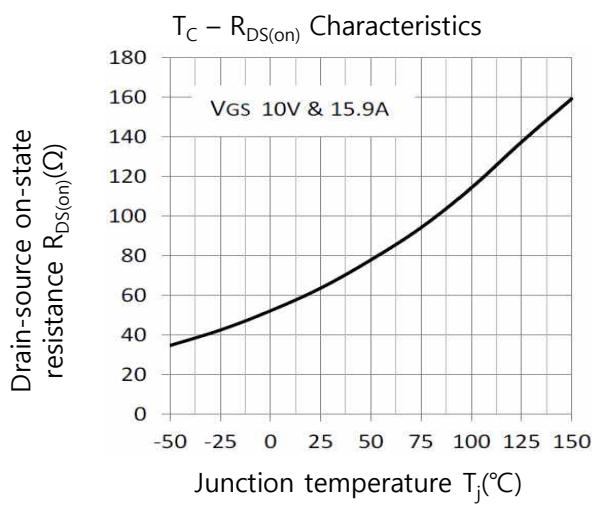
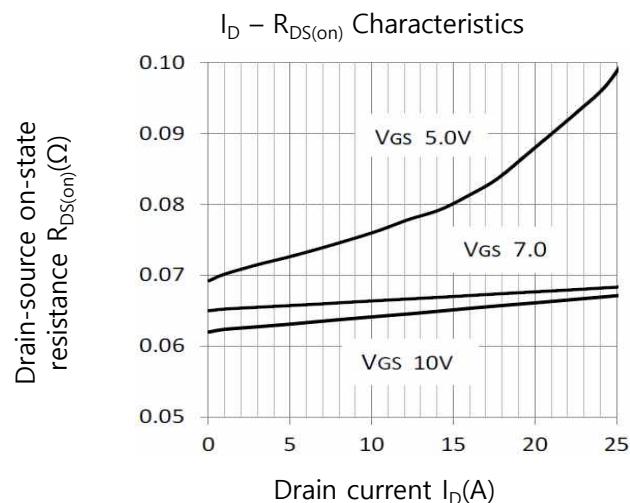
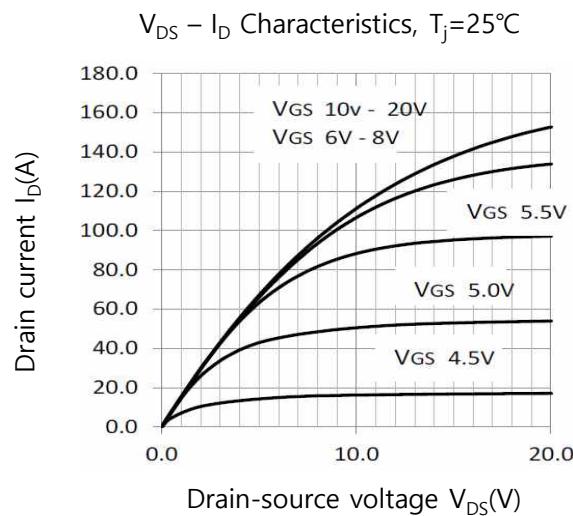

**Body diode(source – drain) electrical characteristics ( $T_C = 25^\circ\text{C}$ )**

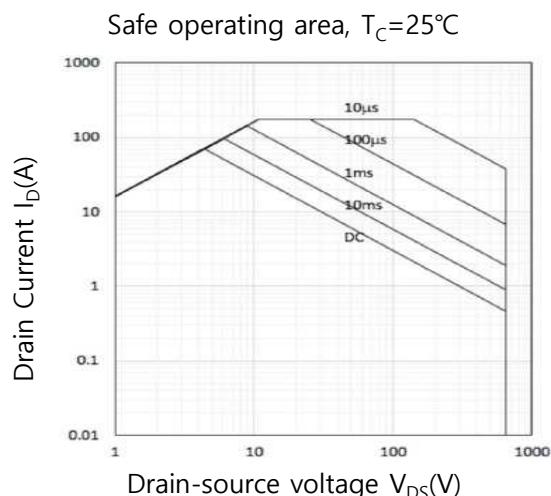
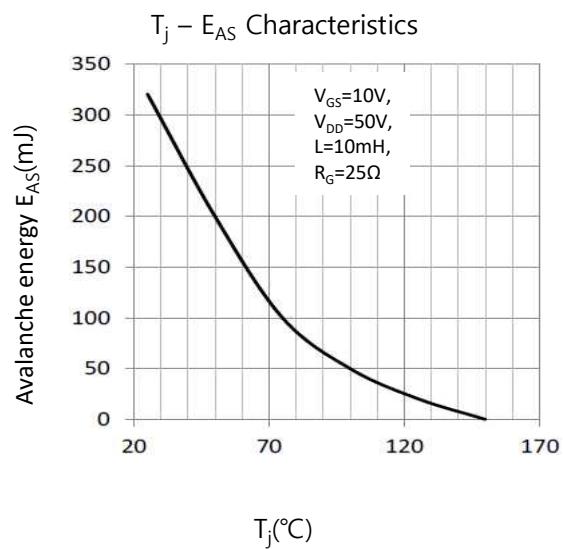
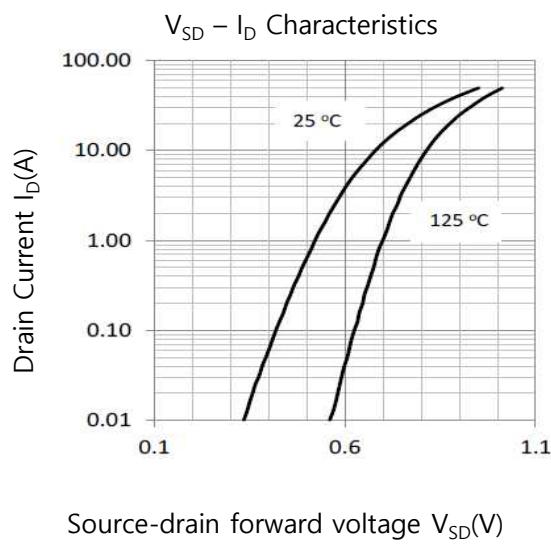
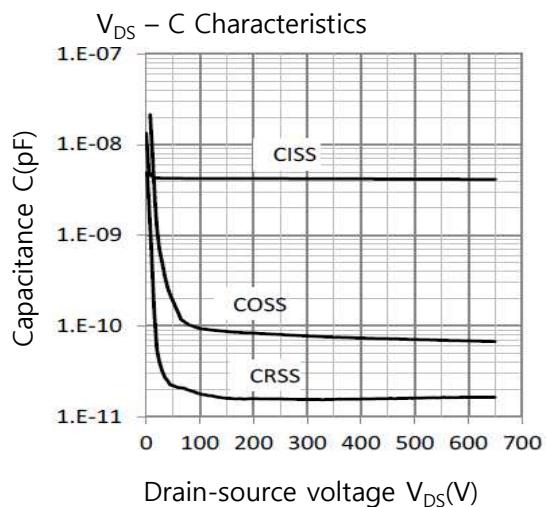
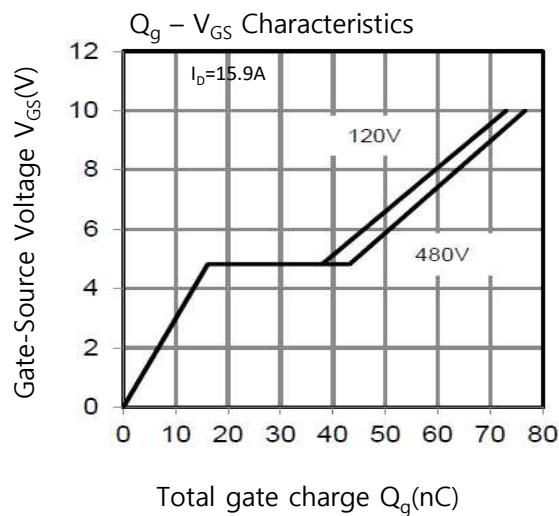
Parameter	Symbol	Test condition	Value			Unit
			Min	Typ	Max	
Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_{SD}=31.8\text{A}$	-	0.95	-	V
Continuous diode forward current	$I_S$	$V_{GS}=0\text{V}, T_C=25^\circ\text{C}$	-	43.6	-	A
Reverse recovery time	$t_{rr}$	$V_{GS}=0\text{V}, I_S=31.8\text{A}, \frac{dI}{dt}=100\text{A}/\mu\text{s}, V_{DD}=60\text{V}$	-	470	-	ns
Reverse recovery charge	$Q_{rr}$		-	10	-	nC
Peak reverse recovery current	$I_{rrm}$		-	50	-	A


**Thermal characteristics ( $T_C = 25^\circ\text{C}$ )**

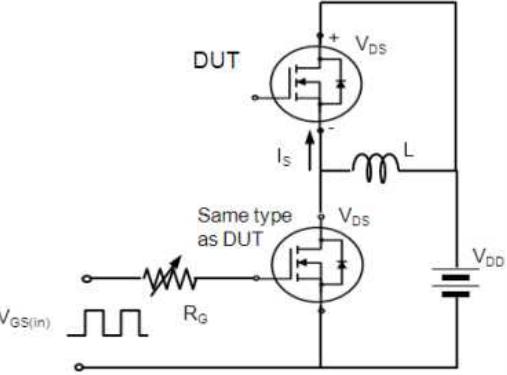
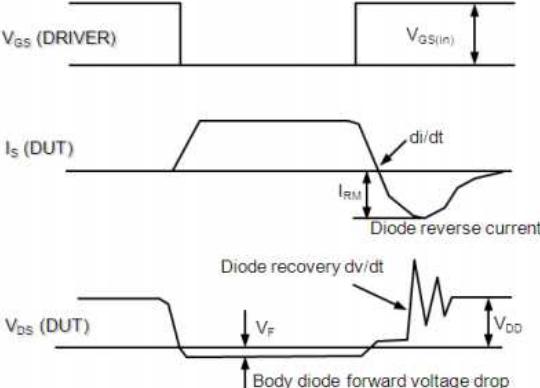
Symbol	Parameter	Typ	Max	Unit
$R_{th(j-c)}$	Junction to case	0.42	0.45	°C/W

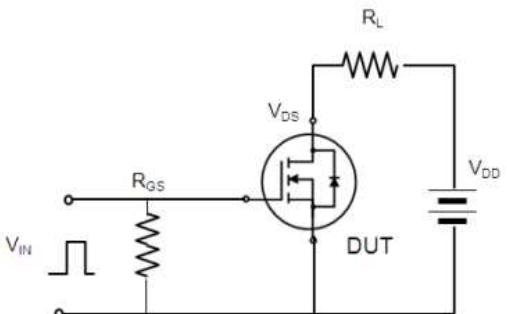
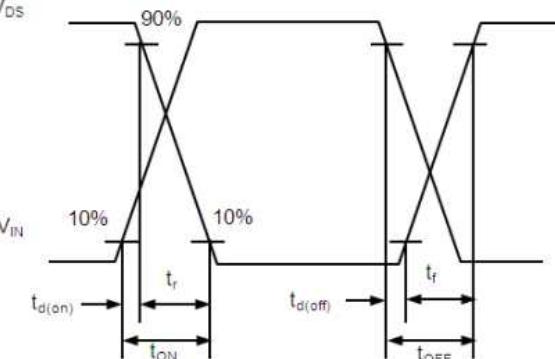



**Typical electrical characteristics curves ( $T_C = 25^\circ\text{C}$ )**


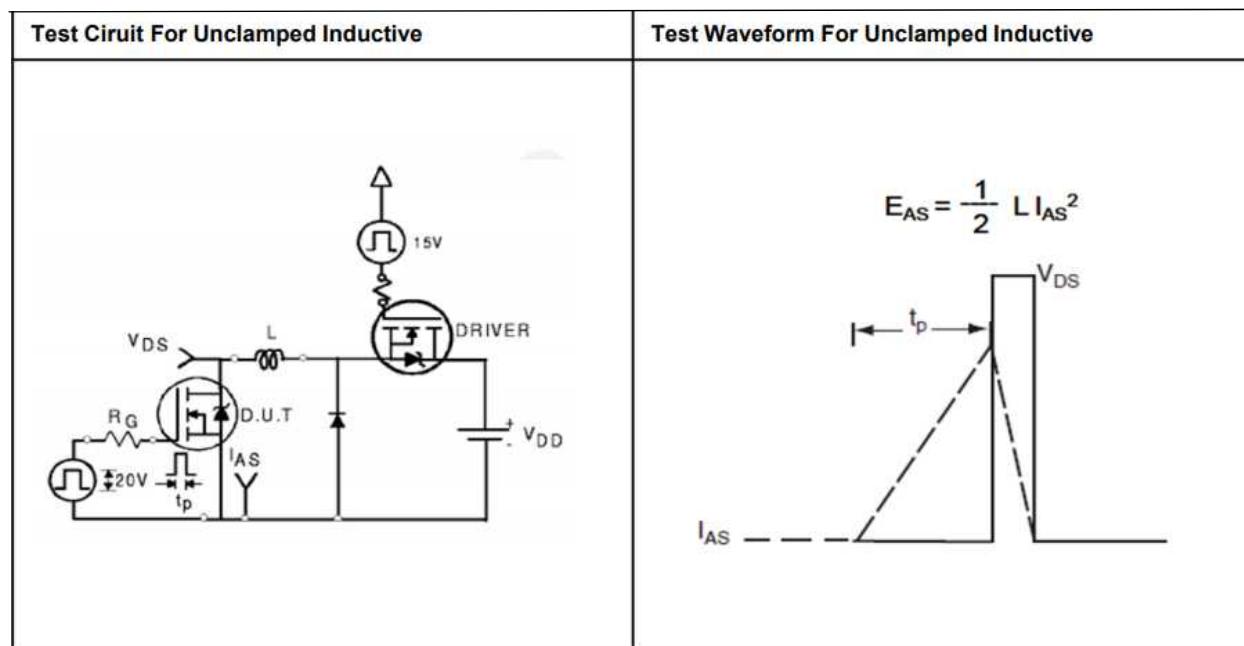
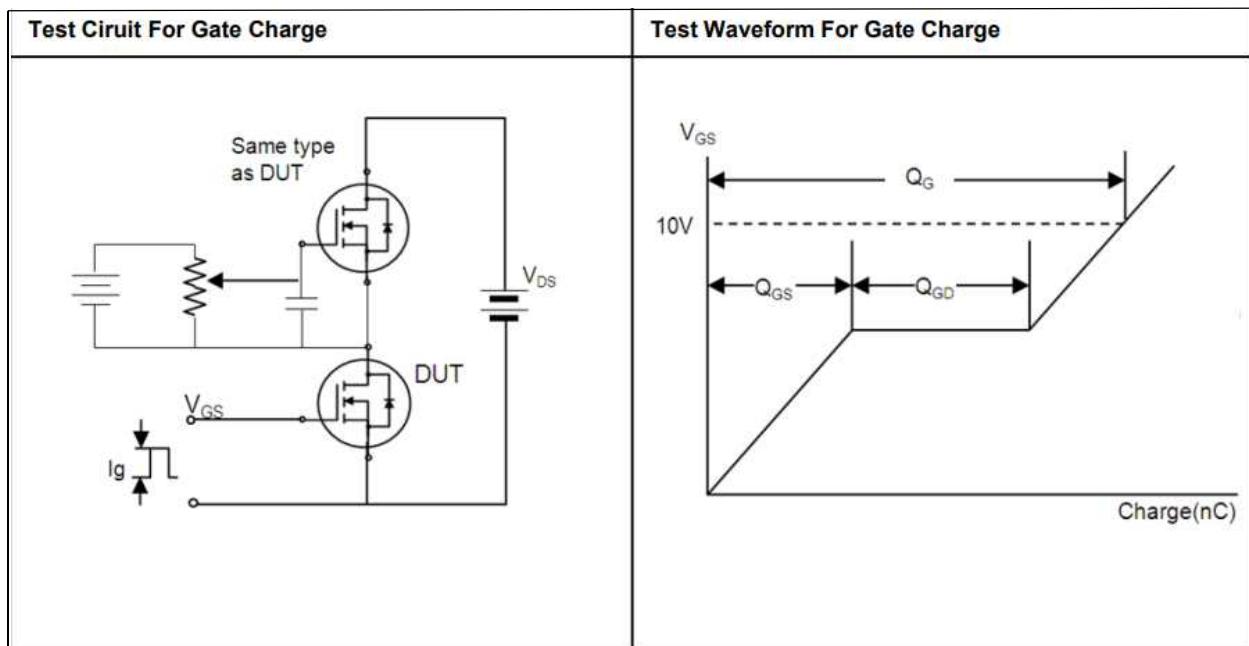

**Typical electrical characteristics curves ( $T_C = 25^\circ\text{C}$ )**



**Typical device performance**

Test Circuit For Diode Recovery	Test Waveform For Diode Recovery
 <p>* <math>\frac{dv}{dt}</math> controlled by <math>R_G</math>  * <math>I_S</math> controlled by pulse period</p>	 <p>V<sub>GS</sub> (DRIVER)  V<sub>GS(in)</sub></p> <p>I<sub>S</sub> (DUT)</p> <p>I<sub>RM</sub>      di/dt  Diode reverse current</p> <p>V<sub>DS</sub> (DUT)</p> <p>V<sub>F</sub>      Body diode forward voltage drop</p>

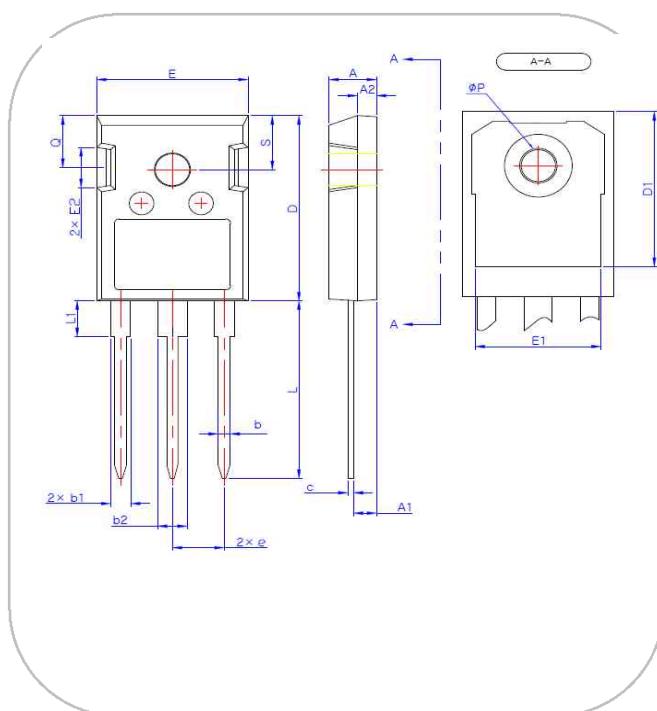
Test Circuit for Switching Time	Test Waveform for Switching Time
	 <p>V<sub>DS</sub></p> <p>V<sub>IN</sub></p> <p>90%</p> <p>10%</p> <p>t<sub>d(on)</sub>      t<sub>ON</sub></p> <p>t<sub>f</sub>      t<sub>d(off)</sub></p> <p>t<sub>OFF</sub></p>




**Typical device performance**




## Package dimensions (TO-247)



Symbol	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.29	2.36	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.91	2.11	2.20
b2	2.92	3.10	3.20
c	0.50	0.60	0.70
D	20.80	21.07	21.34
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.06	13.26	13.46
E2	4.32	4.58	4.83
e	5.45 BSC		
L	19.85	20.00	20.25
L1	-	-	4.49
ΦP	3.55	3.60	3.65
Q	5.59	5.89	6.19
S	6.15 BSC		



## Marking Information

